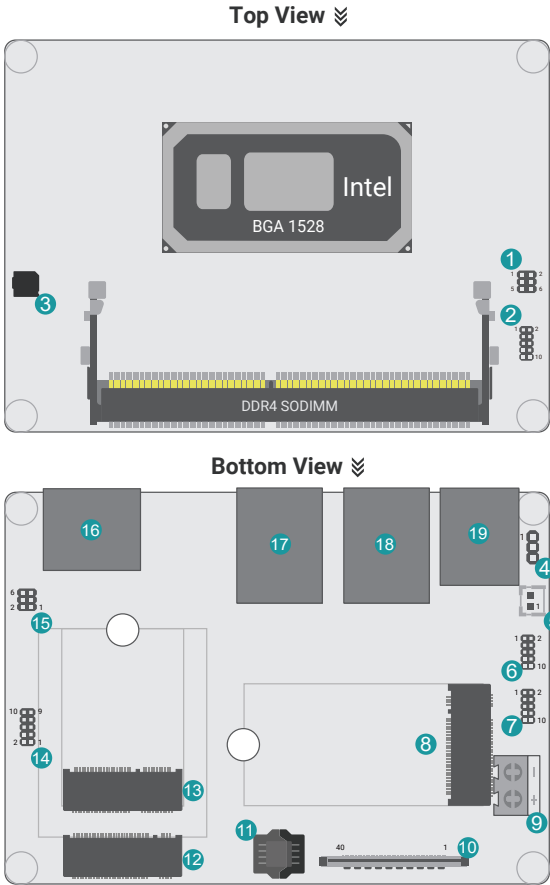


Board Layout



- 1 SMBus
- 2 Front Audio
- 3 Buzzer
- 4 JP1
- 5 Battery
- 6 USB 6/7 (USB 2.0)
- 7 DIO
- 8 M.2 B Key 3042
- 9 12VDC-In
- 10 eDP
- 11 SPI Flash BIOS
- 12 M.2 B Key 3042
- 13 M.2 E Key 2230
- 14 COM1
- 15 Front Panel
- 16 DP/DP++/HDMI
- 17 LAN1
- 18 LAN2
- 19 2 x USB 3.1 Gen2

Jumper Settings

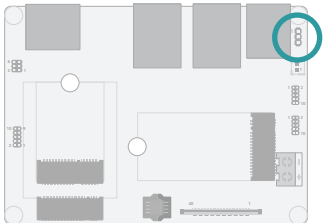
4 Clear CMOS (JP1)



1-2 On: Normal (default)



2-3 On: Clear CMOS



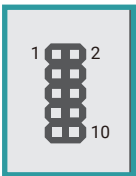
Pin Assignments

1 SMBus



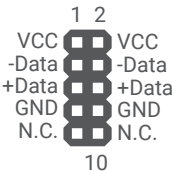
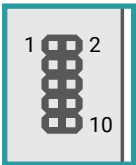
Pin	Assignment	Pin	Assignment
1	3V3SB	2	GND
3	SMBus_Clock	4	SMBus_SDA
5	SMBus_Alert	6	N.C.

2 Front Audio

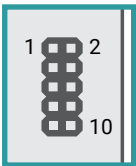


Pin	Assignment	Pin	Assignment
1	MIC2-L	2	GND
3	MIC2-R	4	N.C.
5	LINE2-R	6	MIC2-JD
7	GND	8	N.C.
9	LINE2-L	10	LINE2-JD

6 USB 6/7 (USB 2.0)

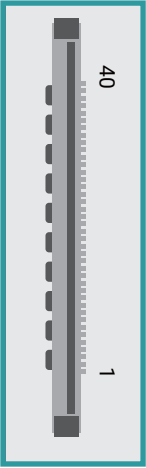


7 DIO



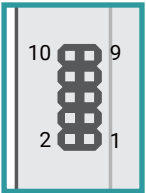
Pin	Assignment	Pin	Assignment
1	DIO_7	2	DIO_6
3	DIO_5	4	DIO_4
5	DIO_3	6	DIO_2
7	DIO_1	8	DIO_0
9	5V	10	GND

10 eDP



Pin	Function	Pin	Function
1	N.C.	21	Panel Power
2	GND	22	N.C.
3	eDP_TX3-	23	GND
4	eDP_TX3+	24	GND
5	GND	25	GND
6	eDP_TX2-	26	GND
7	eDP_TX2+	27	eDP_HPD
8	GND	28	GND
9	eDP_TX1-	29	GND
10	eDP_TX1+	30	GND
11	GND	31	GND
12	eDP_TX0-	32	Backlight On/Off
13	eDP_TX0+	33	Dimming
14	GND	34	N.C.
15	eDP_AUX+	35	N.C.
16	eDP_AUX-	36	Inverter Power
17	GND	37	Inverter Power
18	Panel Power	38	Inverter Power
19	Panel Power	39	Inverter Power
20	Panel Power	40	N.C.

14 COM1



Pin	RS232	RS422	RS485
1	DCD-	TXD-	Data-
2	SIN	TXD+	Data+
3	SOUT	RXD+	N.C.
4	DTR-	RXD-	N.C.
5	GND	GND	GND
6	DSR-	N.C.	N.C.
7	RTS-	N.C.	N.C.
8	CTS-	N.C.	N.C.
9	RI-	N.C.	N.C.
10	GND	GND	GND

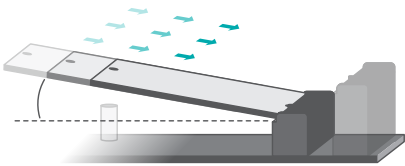
15 Front Panel



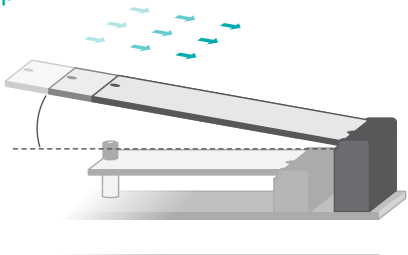
Pin	Assignment	Pin	Assignment
1	PWSIN	2	3V3SB
3	GND	4	SUS_LED
5	RESET	6	HD_LED

M.2 Stack Installation

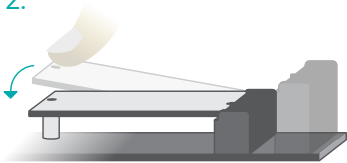
Step 1:



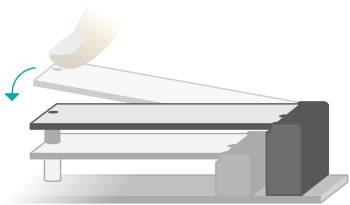
Step 4:



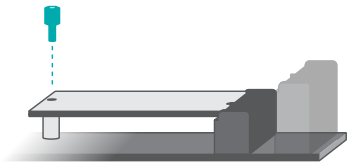
Step 2:



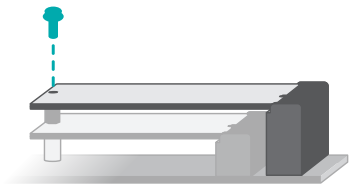
Step 5:



Step 3:

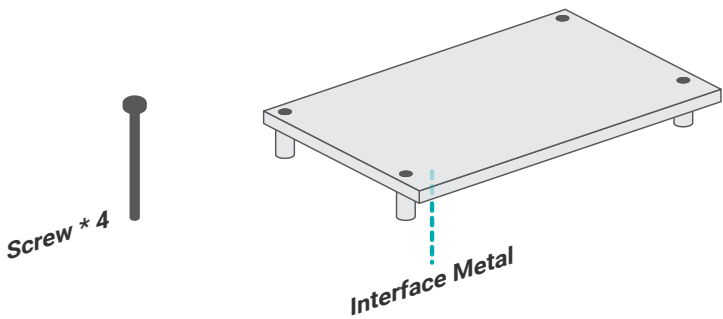


Step 6:

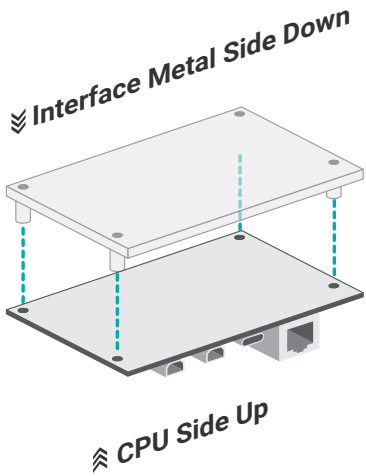


Assembly

A heat spreader is included in the standard package. The heat spreader and components required for mounting are illustrated below.



The heat spreader is designed to be mounted onto the module as illustrated below. Please make sure the contacting sides of the heat spreader and the module are correct — the CPU side of the module shall be facing the interface metal side and legs of the heat spreader. Rotate horizontally so the interface metal sits right on top of the CPU. Remove any plastic cover on the interface metal and apply thermal paste/adhesive if it is required.

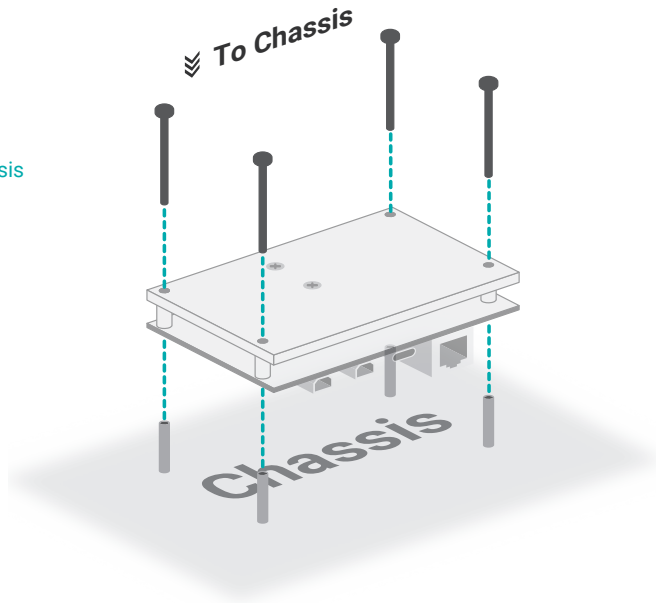


Rotate the module and heat spreader combo so that the I/O is facing the desired side, and place the combo in the position of the chassis reserved for your module.

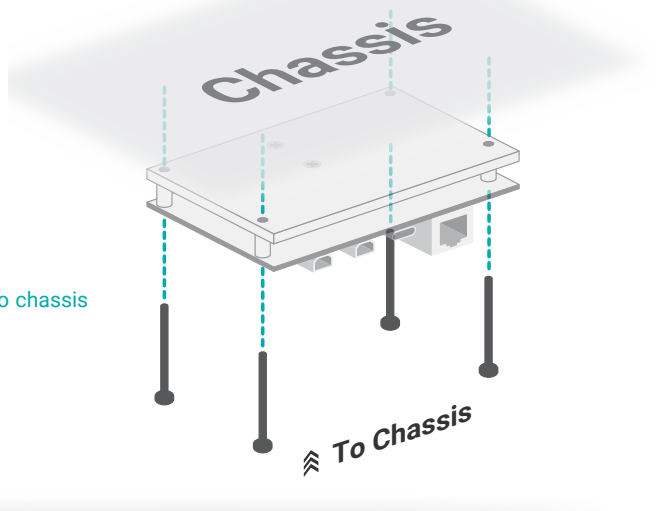
Align the screw holes of the combo to those on the chassis. The combo can be mounted onto the chassis in two manners — 1) module side to the chassis, or 2) heat spreader side to the chassis as illustrated below. This shall depend entirely on the design of the chassis with regard to interior spacing, thermal, and I/O.

Place the screws that come with the standard package into the screw holes, and use a screw driver to fasten the screws until the combo is securely fixed onto the chassis.

■ Module side to chassis



■ Heat spreader side to chassis



DFI reserves the right to change the specifications at any time prior to the product's release. This QR may be based on editions that do not resemble your actual products. For more documentation and drivers, please visit the download page at <https://go.dfi.com/WL051>, or via the QR code to the right.

